

Material Set Change Description:

Package	Material	CARSEM	AMKOR
SOT23 Chip-On-Lead 5/6/8Lead	Mold Compound	Hitachi CEL8240HF10LX	Sumitomo G700LS

Mold Surface Finish: Smooth Surface Finish (Carsem) - Matte Surface Finish (Amkor)

Qualification Results Summary of SOT-23 Chip-on-Lead Package at Amkor Philippines

QUALIFICATION PLAN / STATUS			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	Pass
Temperature/Humidity/Bias (THB)*	JEDEC <i>JESD22-A101</i>	3 x 77	Pass
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 77	Pass
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	3 x 77	Pass
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	Pass
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	Pass ±1250V

*Preconditioned per JEDEC/IPC J-STD-020